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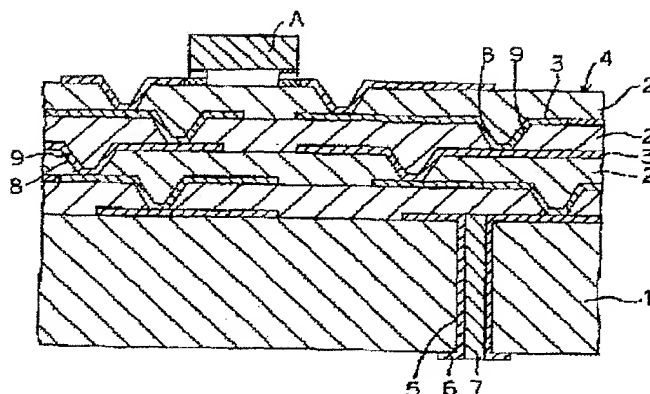
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TITLE : WIRING BOARD



ABSTRACT : PROBLEM TO BE SOLVED: To prevent the infiltration of noises into electronic components such as semiconductor devices which are installed via wiring conductor layers by forming a magnetic area, containing magnetic powder on a part of the wiring conductor layers which covers an organic resin insulating layer.

SOLUTION: A substrate 1 is made of oxide base ceramics, such as an aluminum oxide sintered compact and mullite sintered compact. The substrate 1 supports a multilayered wiring part 4 comprised of organic resin insulating layers 2 and wiring conductor layers 3 on its top. A through-hole 5 is formed in the substrate 1, and its inner walls are coated with a conductive layer 6 whose ends are led out to both upper and lower sides of the substrate 1. The through-hole 5 electrically connects between the wiring conductor layers 3 of the multilayered wiring part 4 formed on the top of the substrate 1 and outer electrical circuits. The through-hole 5 is completely filled with an organic resin filler 7 of epoxy resin or the like. Both ends of the organic resin filler 7 are on flush with the surface of the conductive layer 6 which covers both the upper and lower sides of the substrate 1. Accordingly, the organic resin insulating layers 2 and the wiring conductor layers 3 can be planarized.

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